2116 FAMILY

16,384 X 1 BIT DYNAMIC RAM

	2116-2	2116-3	2116-4
Max. Access Time (ns)	200	250	300
Read, Write Cycle (ns)	350	375	425
Read-Modify-Write Cycle (ns)	400	525	595

- **Highest Density 16K RAM: Industry Standard 16 Pin Package**
- **Low Standby Power**
- **All Inputs Including Clocks TTL Compatible**
- **±10% Tolerance on all Power Supplies +12V, +5V, −5V**
- **On-Chip Latches for Address and Data In**
- **Only 64 Refresh Cycles Required Every 2 ms**
- **Output is Three-State, TTL Compatible; Data is Latched and Valid into Next Cycle**

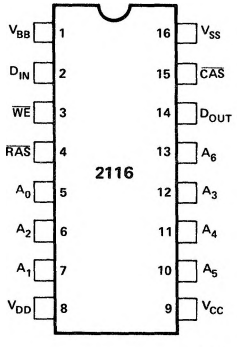
The Intel® 2116 is a 16,384 word by 1 bit MOS RAM fabricated with two layer polysilicon N-MOS technology — a production-proven process for high performance, high reliability, and high functional density. The 2116 uses a single transistor dynamic storage cell and dynamic circuitry to achieve high speed and low power dissipation.

The unique design of the 2116 allows it to be packaged in the industry standard 16 pin dual-in-line package. The 16 pin package provides the highest system bit densities and is compatible with widely available automated handling equipment. The 2116 is designed to facilitate upgrading of 2104A-type 4K RAM systems to 16K capabilities.

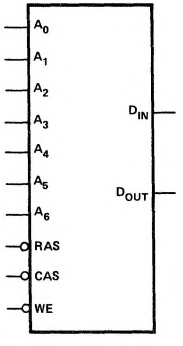
The use of the 16 pin package is made possible by multiplexing the 14 address bits (required to address 1 of 16,384 bits) into the 2116 on 7 address input pins. The two 7 bit address words are latched into the 2116 by the two TTL clocks, Row Address Strobe ($\overline{RAS}$) and Column Address Strobe ($\overline{CAS}$). Non-critical clock timing requirements allow use of the multiplexing technique while maintaining high performance.

The single transistor dynamic storage cell provides high speed along with low power dissipation. The memory cell requires refreshing for data retention. Refreshing can be accomplished every 2 ms by any one of the three following methods: (1) $\overline{CAS}$ before $\overline{RAS}$ cycles on 64 addresses, A_0–A_5, (2) $\overline{RAS}$-only cycles on 128 address, A_0–A_6, or (3) normal read or write cycles on 128 addresses, A_0–A_6. A write cycle will refresh stored data on all bits of the selected row except the bit which is addressed. The output is brought to a high impedance state by a $\overline{CAS}$-only cycle or by a $\overline{CAS}$-before-$\overline{RAS}$ refresh cycle.

PIN CONFIGURATION



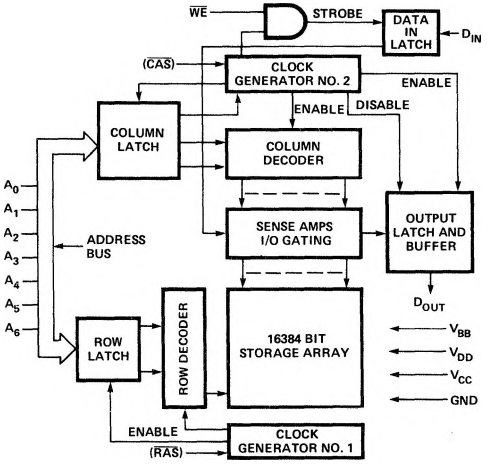
LOGIC SYMBOL



PIN NAMES

A_0 - A_6	ADDRESS INPUTS	$\overline{WE}$	WRITE ENABLE
$\overline{CAS}$	COLUMN ADDRESS STROBE	V_{BB}	POWER (-5V)
D_{IN}	DATA IN	V_{CC}	POWER (+5V)
D_{OUT}	DATA OUT	V_{DD}	POWER (+12V)
$\overline{RAS}$	ROW ADDRESS STROBE	V_{SS}	GROUND

BLOCK DIAGRAM



Absolute Maximum Ratings*

Ambient Temperature Under Bias	-10°C to +80°C
Storage Temperature	-65°C to +150°C
Voltage on any Pin Relative to V_{BB} (V_{SS} - V_{BB} ≥ 4V)	-0.3V to +20V
Power Dissipation	1.25W

*COMMENT:
Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

D.C. and Operating Characteristics [1],[2]

T_A = 0°C to 70°C, V_{DD} = +12V ±10%, V_{CC} = +5V ±10%, V_{BB} = -5V ±10%, V_{SS} = 0V, unless otherwise noted.

Symbol	Parameter	Limits Min.	Limits Typ.[3]	Limits Max.	Unit	Conditions	
I_{LI}	Input Load Current (any input)			10	µA	V_{IN} = $V_{IL\ MIN}$ to $V_{IH\ MAX}$	
$\|I_{LO}\|$	Output Leakage Current for high impedance state		0.1	10	µA	Chip deselected: $\overline{RAS}$ and $\overline{CAS}$ at V_{IH} V_{OUT} = 0 to 5.5V	
I_{DD1}	V_{DD} Supply Current		1.2	2	mA	$\overline{CAS}$ and $\overline{RAS}$ at V_{IH} or $\overline{CAS}$-only cycle. Chip deselected prior to measurement. See Note 5.	
I_{BB1}	V_{BB} Supply Current		1	50	µA		
I_{DD2}[4]	Operating V_{DD} Current		53	69	mA	2116-2 t_{CYC} = 350 ns	T_A = 25°C Device selected. See Note 6.
			51	68	mA	2116-3 t_{CYC} = 375 ns	
			49	65	mA	2116-4 t_{CYC} = 425 ns	
I_{BB2}	Operating V_{BB} Current		120	400	µA	Device selected	
I_{CC1}[7]	V_{CC} Supply Current when deselected			10	µA		
V_{IL}	Input Low Voltage (any input)	-1.0		0.8	V		
V_{IH}	Input High Voltage (any input)	2.4		V_{CC}+1	V		
V_{OL}	Output Low Voltage	0.0		0.4	V	I_{OL} = 4.1 mA (Read Cycle Only)	
V_{OH}	Output High Voltage	2.4		V_{CC}	V	I_{OH} = -5 mA (Read Cycle Only)	

Capacitance [8] T_A = 25°C, V_{DD} = 12V ±10%, V_{CC} = 5V ±10%, V_{BB} = -5V ±10%, V_{SS} = 0V, unless otherwise noted.

Symbol	Parameter	Typ.	Max.	Unit	Conditions
C_{I1}	Address, Data In & $\overline{WE}$ Capacitance	4	7	pF	V_{IN} = V_{SS}
C_{I2}	$\overline{RAS}$ Capacitance	3	5	pF	V_{IN} = V_{SS}
C_{I3}	$\overline{CAS}$ Capacitance	6	10	pF	V_{IN} = V_{SS}
C_O	Data Output Capacitance	3	7	pF	V_{OUT} = 0V

Notes:
1. All voltages referenced to V_{SS}. No power supply sequencing is required but V_{DD}, V_{CC}, and V_{SS} should never be 0.3V or more negative than V_{BB}.
2. To avoid self-clocking, $\overline{RAS}$ should not be allowed to float.
3. Typical values are for T_A = 25°C and nominal power supply voltages.
4. For $\overline{RAS}$-only refresh I_{DD} = 0.78 I_{DD2}. For $\overline{CAS}$-before-$\overline{RAS}$ (64 cycle refresh) I_{DD} = 0.96 I_{DD2}.
5. The chip is deselected (i.e., output is brought to high impedance state) by $\overline{CAS}$-only cycle or by $\overline{CAS}$-before-$\overline{RAS}$ cycle. The current flowing in a selected (i.e., output on) chip with $\overline{RAS}$ and $\overline{CAS}$ at V_{IH} is approximately twice I_{DD1}.
6. See Page 2-98 for typical I_{DD} characteristics under other conditions.
7. When chip is selected V_{CC} supply current is dependent on output loading; V_{CC} is connected to output buffer only.
8. Capacitance measured with Boonton Meter.

Typical Characteristics

I_{BB2} AND I_{DD2} VS. TEMPERATURE

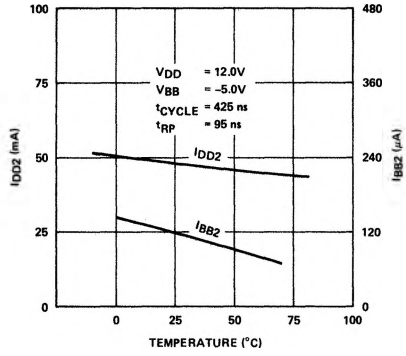


Figure 1.

I_{DD2} VS. CYCLE TIME

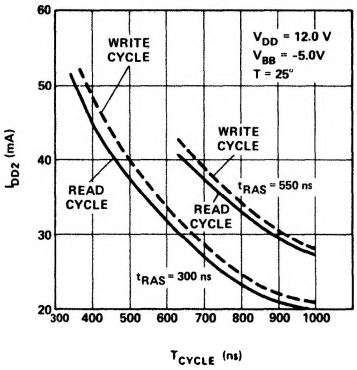


Figure 2.

Standby Power Calculations:

$$P_{REF} = P_{OP}\left(N\frac{t_{CYC}}{t_{REF}}\right) + P_{SB}\left(1 - N\frac{t_{CYC}}{t_{REF}}\right)$$ where

P_{OP} = Power dissipation (continuous operation) $\cong V_{DD} \times I_{DD2}$.

N = Number of refresh cycles (64 or 128)

t_{CYC} = Cycle time for a refresh cycle.

t_{REF} = Time between refreshes

P_{SB} = Standby power dissipation = $V_{DD} \times I_{DD1} + |V_{BB}| \times I_{BB}$

Note that I_{DD2} depends upon refresh as follows:

1. For 128 cycle ($\overline{RAS}$ before $\overline{CAS}$) use I_{DD2} from Figures 1 and 2.
2. For 64 cycle ($\overline{CAS}$ before $\overline{RAS}$) multiply I_{DD2} determined in (1) by 0.96.
3. For 128 cycle ($\overline{RAS}$ only) multiply I_{DD2} determined in (1) by 0.78.

Examples of typical calculations for V_{BB} = -5.0V, V_{DD} = 12.0V, T_A = 25°C, t_{CYC} = 0.425 μs, t_{RAS} = 0.3 μs. t_{REF} = 2000 μs:

1. 128 cycle ($\overline{RAS}$ before $\overline{CAS}$): P_{OP} = 12.0V x 43 mA = 516 mW

   $$P_{REF} = 516\left(128\frac{0.425}{2000}\right) + (12x1.2+5x0.001)\left(1-128\frac{0.425}{2000}\right)$$

   P_{REF} = 28.0 mW

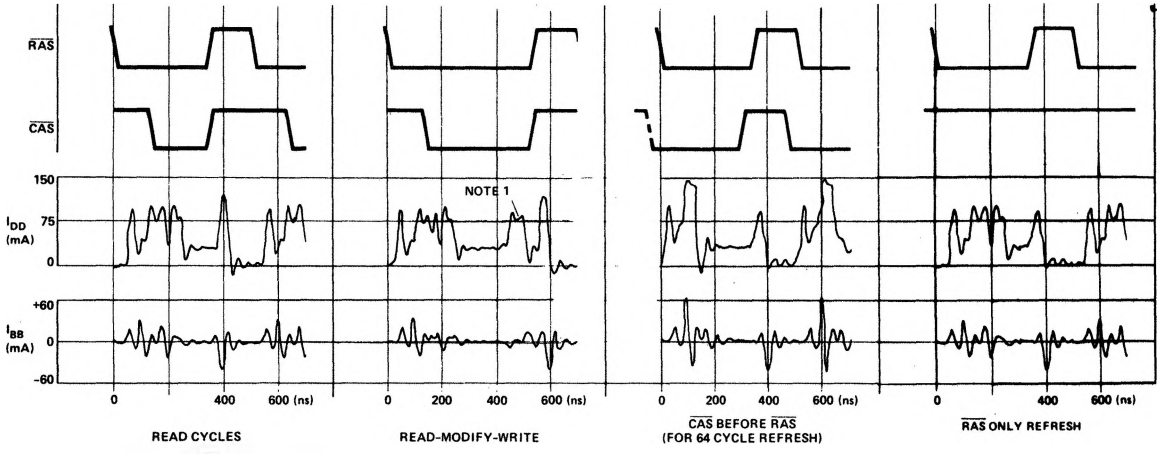
2. 64 cycle ($\overline{CAS}$ before $\overline{RAS}$); P_{OP} = 12.0V x 43 (0.96) mA = 495 mW.

   $$P_{REF} = 495\left(64\frac{0.425}{2000}\right) + (12x1.2+5x0.001)\left(1-64\frac{0.425}{2000}\right) =$$

   P_{REF} = 20.9 mW

3. 128 cycle ($\overline{RAS}$ only): P_{OP} = 12.0V x 43 (0.78) mA = 402 mW

   P_{REF} = 25.0 mW



Note 1: Increase in current due to $\overline{WE}$ going low. Width of this current pulse is independent of $\overline{WE}$ pulse width.

Figure 3. Supply Current Waveforms.

A.C. Characteristics[1]

T_A=0°C to 70°C, V_{DD}=12V ±10%, V_{CC}=5V ±10%, V_{BB}=−5V ±10%, V_{SS}=0V, unless otherwise noted.

READ, WRITE, READ-MODIFY-WRITE AND REFRESH CYCLES

Symbol	Parameter	2116-2 Min.	2116-2 Max.	2116-3 Min.	2116-3 Max.	2116-4 Min.	2116-4 Max.	Unit
t_{REF}	Time Between Refresh		2		2		2	ms
t_{RP}	$\overline{RAS}$ Precharge Time	75		75		95		ns
t_{CP}	$\overline{CAS}$ Precharge Time	100		125		125		ns
t_{RCL}[2]	$\overline{RAS}$ to $\overline{CAS}$ Leading Edge Lead Time	45	75	50	110	60	110	ns
t_{CRP}[3]	$\overline{CAS}$ to $\overline{RAS}$ Precharge Time	0		0		0		ns
t_{RSH}	$\overline{RAS}$ Hold Time	160		200		220		ns
t_{CSH}	$\overline{CAS}$ Hold Time	200		250		300		ns
t_{ASR}	Row Address Set-Up Time	0		0		0		ns
t_{ASC}	Column Address Set-Up Time	−10		−10		−10		ns
t_{AH}	Address Hold Time	45		50		60		ns
t_T	Transition Time (Rise and Fall)		50		50		50	ns
t_{OFF}	Output Buffer Turn Off Delay	0	60	0	60	0	80	ns
t_{CAC}[4]	Access Time From $\overline{CAS}$		125		150		190	ns
t_{RAC}[4]	Access Time From $\overline{RAS}$		200		250		300	ns

READ AND REFRESH CYCLES

Symbol	Parameter	2116-2 Min.	2116-2 Max.	2116-3 Min.	2116-3 Max.	2116-4 Min.	2116-4 Max.	Unit
t_{CYC}[5]	Random Read Cycle Time	350		375		425		ns
t_{RAS}	$\overline{RAS}$ Pulse Width	275	32000	300	32000	330	32000	ns
t_{CAS}	$\overline{CAS}$ Pulse Width	125	10000	150	10000	190	10000	ns
t_{CH}	$\overline{CAS}$ Hold Time for $\overline{RAS}$-Only Refresh	30		30		30		ns
t_{CPR}	$\overline{CAS}$ Precharge for 64 Cycle Refresh	30		30		30		ns
t_{RCH}	Read Command Hold Time	20		20		20		ns
t_{RCS}	Read Command Set-Up Time	0		0		0		ns
t_{DOH}	Data-Out Hold Time	32		32		32		μs

WRITE CYCLE

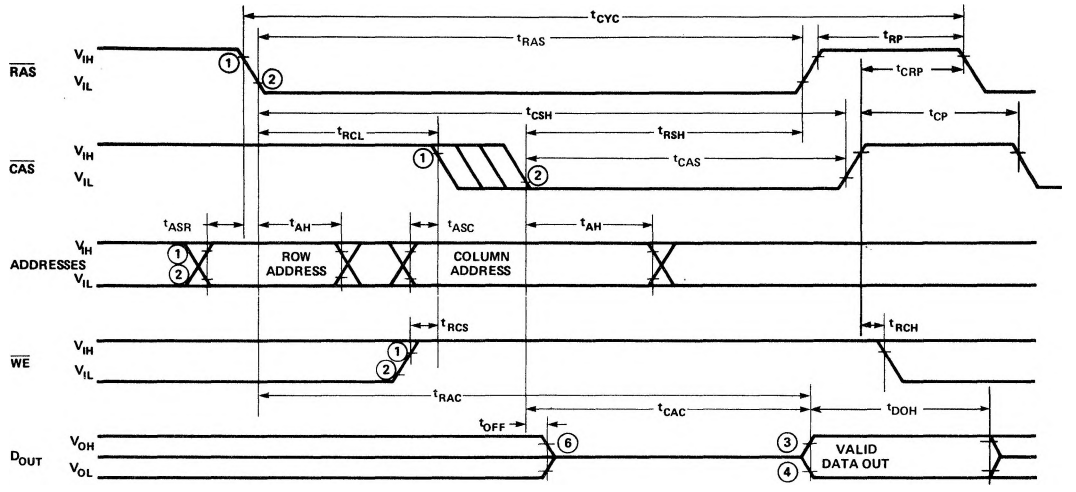
Symbol	Parameter	2116-2 Min.	2116-2 Max.	2116-3 Min.	2116-3 Max.	2116-4 Min.	2116-4 Max.	Unit
t_{CYC}[5]	Random Write Cycle Time	350		375		425		ns
t_{RAS}	$\overline{RAS}$ Pulse Width	275	32000	300	32000	330	32000	ns
t_{CAS}	$\overline{CAS}$ Pulse Width	125	10000	150	10000	190	10000	ns
t_{WCH}	Write Command Hold Time	75		100		100		ns
t_{WP}	Write Command Pulse Width	50		100		100		ns
t_{RWL}	Write Command to $\overline{RAS}$ Lead Time	125		200		200		ns
t_{CWL}	Write Command to $\overline{CAS}$ Lead Time	100		150		160		ns
t_{DS}[6]	Data-In Set-Up Time	0		0		0		ns
t_{DH}[6]	Data-In Hold Time	100		100		125		ns

Notes:

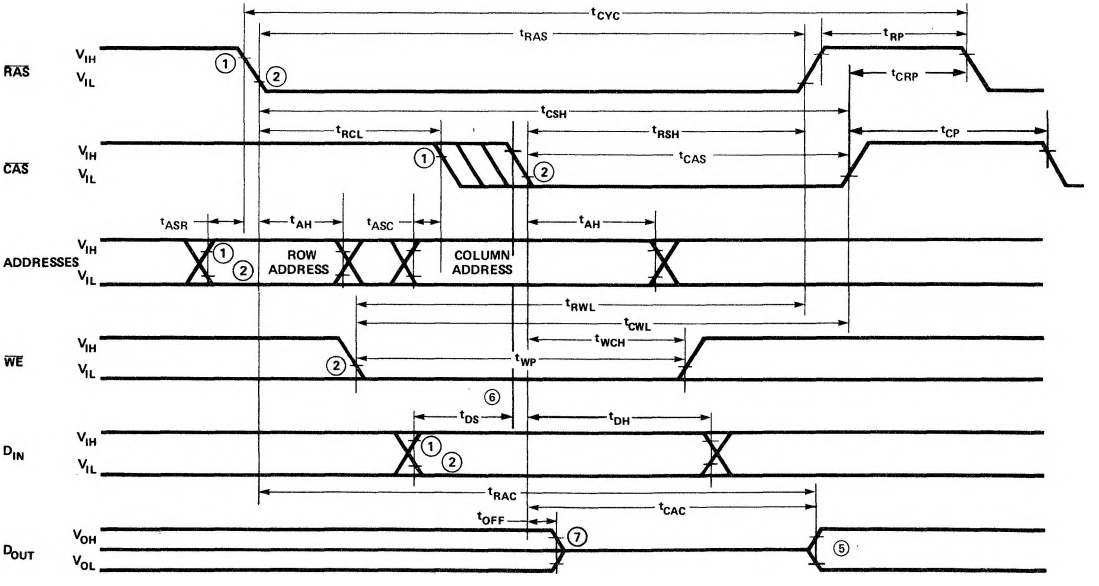
1. All voltages referenced to V_{SS}.
2. $\overline{CAS}$ must remain at V_{IH} a minimum of $t_{RCL\ MIN}$ after $\overline{RAS}$ switches to V_{IL}. To achieve the minimum guaranteed access time (t_{RAC}), $\overline{CAS}$ must switch to V_{IL} at or before $t_{RCL\ (MAX)} = t_{RAC} - t_{CAC}$. Device operation is not guaranteed for $t_{RCL} > 2$ μs.
3. The t_{CRP} specification is less restrictive than the t_{CRL} range which was specified in the 2116 preliminary data sheet.
4. Load = 1 TTL and 50 pF.
5. The minimum cycle timing does not allow for t_T or skews.
6. Referenced to $\overline{CAS}$ or $\overline{WE}$, whichever occurs last.

Waveforms

READ CYCLE



WRITE CYCLE



Notes:
1,2. $V_{IH\ MIN}$ and $V_{IL\ MAX}$ are reference levels for measuring timing of input signals.
3,4. $V_{OH\ MIN}$ and $V_{OL\ MAX}$ are reference levels for measuring timing of D_{OUT}.
5. D_{OUT} follows D_{IN} when writing, with $\overline{WE}$ before $\overline{CAS}$.
6. Referenced to $\overline{CAS}$ or $\overline{WE}$, whichever occurs last.
7. t_{OFF} is measured to $I_{OUT} \leq |I_{LO}|$.

A.C. Characteristics

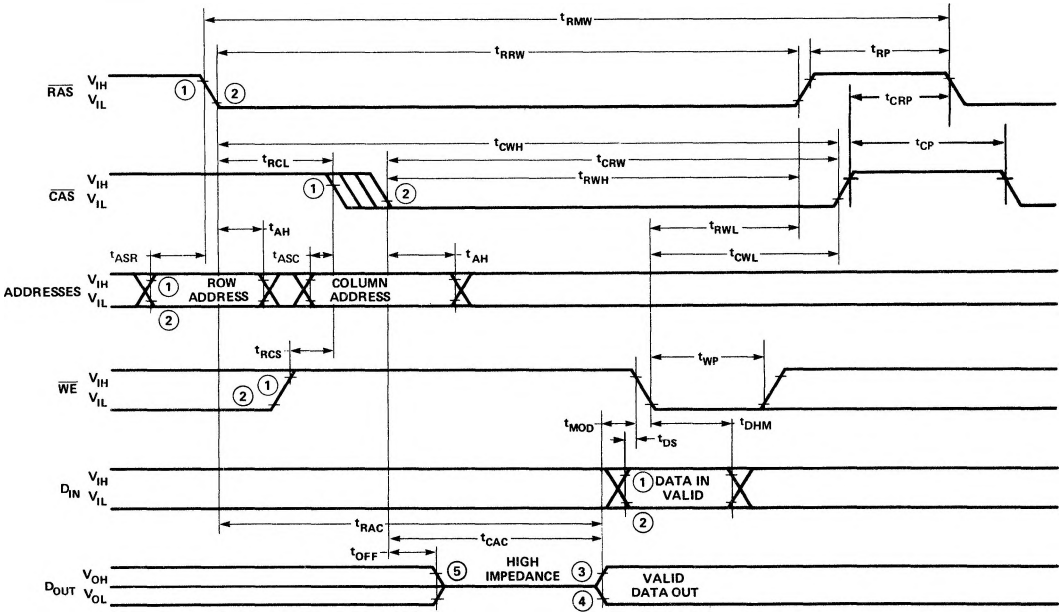
T_A = 0°C to 70°C, V_{DD} = 12V ±10%, V_{CC} = 5V ±10%, V_{BB} = −5V ±10%, V_{SS} = 0V, unless otherwise noted.

READ-MODIFY-WRITE CYCLE

Symbol	Parameter	2116-2 Min.	2116-2 Max.	2116-3 Min.	2116-3 Max.	2116-4 Min.	2116-4 Max.	Unit
t_{RMW}	Read-Modify-Write Cycle Time	400		525		595		ns
t_{CRW}	RMW Cycle $\overline{CAS}$ Width	225	10000	310	10000	350	10000	ns
t_{RRW}	RMW Cycle $\overline{RAS}$ Width	325	32000	450	32000	500	32000	ns
t_{RWH}	RMW Cycle $\overline{RAS}$ Hold Time	250		350		390		ns
t_{CWH}	RMW Cycle $\overline{CAS}$ Hold Time	300		410		460		ns
t_{RWL}	Write Command to $\overline{RAS}$ Lead Time	125		200		200		ns
t_{CWL}	Write Command to $\overline{CAS}$ Lead Time	100		160		160		ns
t_{WP}	Write Command Pulse Width	50		100		100		ns
t_{RCS}	Read Command Set-Up Time	0		0		0		ns
t_{MOD}	Modify Time	0	10	0	10	0	10	μs
t_{DS}	Data-In Set-Up Time	0		0		0		ns
t_{DHM}	Data-In Hold Time (RMW Cycle)	50		100		125		ns

Waveforms

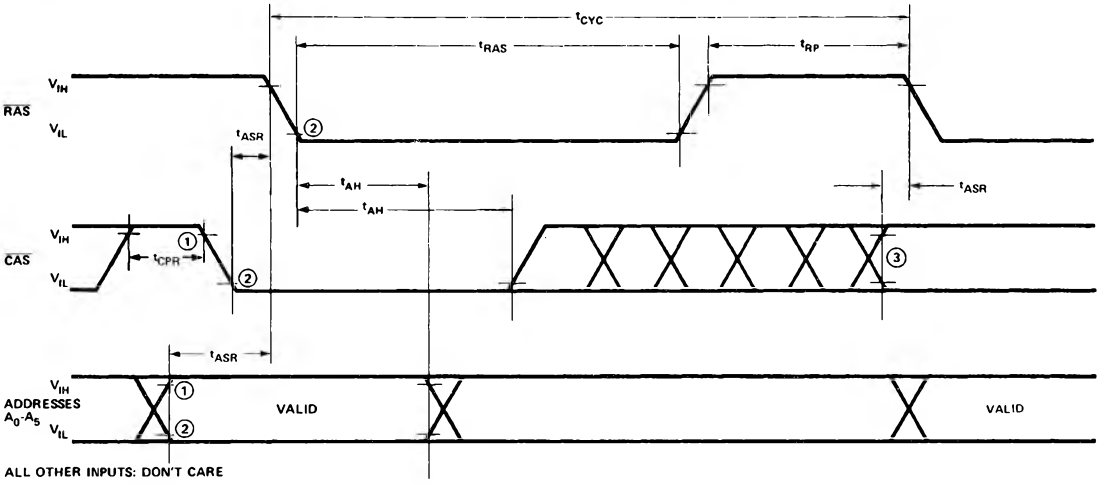
READ MODIFY WRITE CYCLE



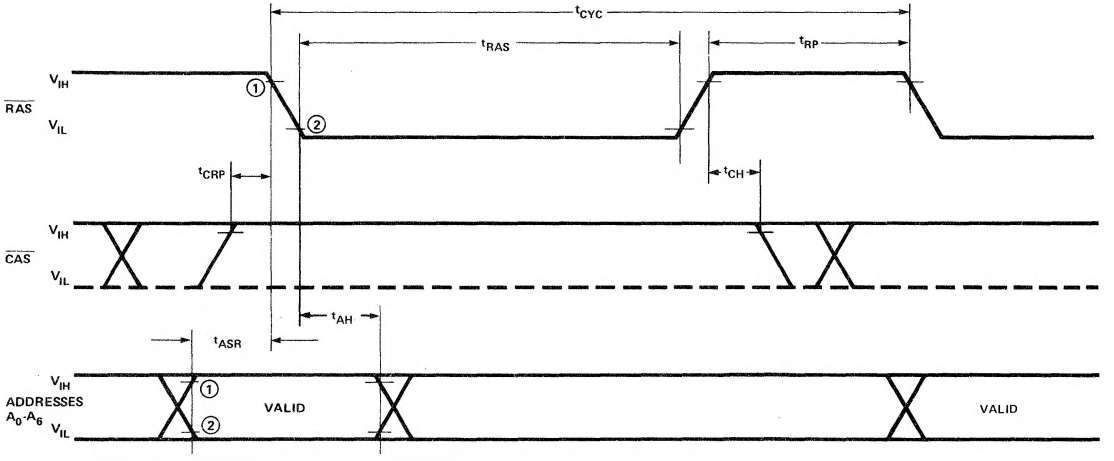
Notes: 1,2. V_{IHMIN} and V_{ILMAX} are reference levels for measuring timing of input signals.
3,4. V_{OHMIN} and V_{OLMAX} are reference levels for measuring timing of D_{OUT}.
5. t_{OFF} is measured to $|I_{OUT}| \leq |I_{LO}|$.

Refresh Cycle Waveforms

$\overline{CAS}$ BEFORE $\overline{RAS}$ CYCLES. (64 CYCLE REFRESH)



$\overline{RAS}$ ONLY CYCLES (128 CYCLE REFRESH)



Notes: 1,2. V_{IHMIN} and V_{ILMAX} are reference levels for measuring timing of input signals.
3. $\overline{CAS}$ must be high or low as appropriate for the next cycle.

Applications Information

REFRESH MODES

The 2116 may be refreshed in any of three modes. Read/Refresh cycles and $\overline{RAS}$-only cycles refresh the row addressed by A_0 through A_6 and therefore require 128 cycles to refresh the stored data. Assuming a 500 nsec system cycle time, the refresh operations require 64 μsec out of each 2.0 msec refresh period or 3.2% of the available memory time. The third 2116 refresh mode, $\overline{CAS}$-before-$\overline{RAS}$, allows refresh of the stored data in only 64 cycles and requires only 32 μsec or 1.6% of the available memory time (equal to the 64-cycle refresh 4K RAMs). While some 2116 aplications would not be impacted by the 3.2% memory lockout time using 128 cycle refresh, most large mainframe memory applications would suffer throughput degradation in that refresh mode. Intel designed the 2116 to allow either 128-cycle or 64-cycle refresh, allowing the system designer to choose the refresh mode which fits his system needs. In addition to allowing higher memory throughput, the $\overline{CAS}$-before-RAS 64-cycle refresh mode dissipates approximately 14% less power than the 128-cycle $\overline{RAS}$-only mode and 23% less power than the 128-cycle Read/Refresh mode (refer to the Standby Power Calculation section).

POWER SUPPLY DECOUPLING/ DISTRIBUTION

Power supply current waveforms for the 2116 are shown in Figure 3. The V_{DD} supply provides virtually all of the operating current for the 2116. The V_{DD} supply current, I_{DD}, has two components: transient current peaks when the clocks change state and a DC component while the clocks are active (low). When selecting the decoupling capacitors for the V_{DD} supply, the characteristics of capacitors as well as the current waveform must be considered. Suppression of transient or pulse currents require capacitors with small physical size and low inherent inductance. Monolithic and other ceramic capacitors exhibit these desirable characteristics. When the current waveform indicates a DC component, bulk capacity must be located near the current load to supply the load power. Inductive effects of PC board traces and bus bars preclude supplying the DC component from bulk capacitors at the periphery of a memory matrix without voltage droop during the active portion of a memory cycle. This means that some bulk capacity in the form of electrolytic or large ceramic capacitors should be distributed around or within the memory matrix.

The V_{BB} supply current, I_{BB}, has high transient current peaks, with essentially no DC component (less than 400 microamperes). The V_{BB} capacitors should be selected for transient suppression characteristics. The following capacitance values and locations are recommended for the 2116:

1. A 0.33 μF ceramic capacitor between V_{DD} and V_{SS} (ground) at every other device.
2. A 0.1 μF ceramic capacitor between V_{BB} and V_{SS} at every other device (preferably alternate devices to the V_{DD} decoupling above).
3. A 4.7 μF electrolytic capacitor between V_{DD} and V_{SS} for each eight devices and located adjacent to the devices.

The V_{CC} supply is connected only to the 2116 output buffer and is not used internally. The load current from the V_{CC} supply is dependent only upon the output loading and is usually only the input high level current to a TTL gate and the output leakage currents of any OR-tied 2116s (typically 100 μA or less total). Intel recommends that a 0.1 or 0.01 μF ceramic capacitor be connected between V_{CC} and V_{SS} for every eight devices to preclude coupled noise from affecting the TTL devices in the system.

Intel recommends a power supply distribution system such that each power supply is grided both horizontally and vertically at each memory device. This technique minimizes the power distribution system impedance and enhances the effect of the decoupling capacitors.

OUTPUT DATA LATCH

The 2116 contains an output data latch eliminating the need for an external system data latch and the timing circuitry required to strobe an external latch. The 2116 output latch operates identically to the output latch found on all industry standard 16-pin, 4K RAMs and enhances the system compatibility of the 16K and 4K devices.

Operation of the output latch is controlled by $\overline{CAS}$. The data output will go to the high-impedance state immediately following the $\overline{CAS}$ leading edge during each data cycle and will either go to valid data at access time on selected devices (devices receiving both $\overline{RAS}$ and $\overline{CAS}$) or will remain in the high impedance state on unselected devices (devices receiving only $\overline{CAS}$). During $\overline{RAS}$-only refresh cycles, the data output remains in the state it was prior to the $\overline{RAS}$-only cycle. This unique feature of latched output RAMs allows a refresh cycle to be hidden among data cycles without impacting data availability. For instance, a $\overline{RAS}$-only refresh cycle could follow each data cycle in a microprocessor system but the accessed data would remain at the device output and the microprocessor could take the data at any time within the cycle. Non-latched output devices do not provide this type of hidden refresh capability since their data output would go to the high impedance state at the end of the data cycle.

PAGE MODE OPERATION

The 2116 is designed for page mode operation and is presently being characterized for that mode. Specifications will be available at a later date.